Tesla, Inc. is looking for IC packaging design engineers and or interns to join our Autopilot hardware group at Tesla. You may find more information of our team as below:

https://www.tesla.com/autopilot

https://electrek.co/2018/08/01/tesla-chip-most-advanced-computer-autonomous-driving-autopilot-hardware-3-update/

Please refer to the job descriptions below.

For interested candidates, please email me at mpang@tesla.com.

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**Position 1:**

**Job Title:** IC Packaging design engineer

**Job Summary**

In this highly visible role, you will own and drive advanced package selection, new product package structure and configuration optimization. You will be responsible for package/SIP layout, optimization, design verification and taping out.

**Key Qualifications**

- Must have good EE fundamentals
- Must have solid signal and power integrity fundamentals
- Experience in package design, design for manufacturing review is nice to have. Familiar with layout review tools such as CAM350/Valor or Calibre is a plus.
- 2D/2.5D and 3D package connection, memory package, stacked die substrate design experience
- Experience preferred in schematic capture, layout and design using Cadence Allegro Schematic Design Entry (Concept HDL) design tools is a plus
- Good exposure to Unix environment, scripting languages (PERL, Python, TCL and/or shell) and methodology
- Ability to innovate in the definition and development of design, verification, and automation strategy to strengthen and streamline package design and release flows

**Description**

- Interface and coordinate with cross-functional groups throughout Tesla on new product package selection, feasibility analysis and design
- Implement the physical design of SoC (system-on-chip)
- Work cross-functionally, understand trade-offs, constraints, and optimizing silicon floor plan, bump and package pin out.
- To optimize signal/power integrity of package design
- Drive methodology, innovations, and productivity improvements in package design together with vendors and developers on feature development and bug resolution
Position 2:
Job Title: IC Packaging Technologist

Role
Seeking an innovative and highly motivated individual to take on Packaging integration role for a variety of projects including SoC, sensors, advanced design which requires path finding technologies.

Responsibility
- Responsible to lead packaging technology development including advanced 2.5D/3D packaging.
- Work with cross functional team and lead SoC Package integration and architecture efforts.
- Work with foundry and OSAT to bring packaging solution from concept to HVM.
- Drive industry with advanced Package solutions, new material development, and specs.
- 5 % International travel.

Key Qualifications
- Good understanding of packaging technologies, assembly processes, IC packaging materials, reliability standards, FA techniques, etc.
- Expert in materials characterization and analysis
- Excellent communication skills that can enable the candidate to work well with internal cross functional teams and overseas suppliers.
- Ability to work independently and take on projects with minimum supervision.
- Excellent engineering problem solving with strong engineering physics.
- Familiar with package design softwares, APD, etc.
- Working knowledge in memory device architecture, design, test, etc.
- Strong program management skill

Education
- Ph.D. or M.S. in Electrical Engineering, Mechanical Engineering, Chemical Engineering, Materials Science or Physics.